

Material Composition Specification

SOT-883 Case

Pb (lead)-free plating



Device average mass **0.86 mg**

Fluctuation margin **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.35%	0.02	Si	7440-21-3	2.35%	0.0202	23500
bond wire	gold	0.83%	0.01	Au	7440-57-5	0.83%	0.0071	8300
leadframe	copper alloy	38.60%	0.33	Cu	7440-50-8	38.60%	0.3320	386000
die attach	silver epoxy	2.37%	0.02	Ag	7440-22-4	1.68%	0.0144	16780
				epoxy resin	Proprietary	0.69%	0.0060	6940
encapsulation	EMC	54.10%	0.47	silica	7631-86-9	50.80%	0.4369	508000
				epoxy resin	Proprietary	3.15%	0.0271	31500
				carbon	1333-86-4	0.15%	0.0013	1500
plating	NiPdAu	1.75%	0.02	Ni	7440-02-0	1.69%	0.0146	16930
				Pd	7440-05-3	0.05%	0.0004	500
				Au	7440-57-5	0.01%	0.0001	70

Disclaimer

The information provided in this Material Composition data sheet is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.